

Abstract**A molding press and a platen for a molding press**

- 5 Disclosed is a platen for a molding press for encapsulating semiconductor dies on a substrate, the platen comprising: a first mold chase having a first mold chase surface; the platen being operable to cooperate with a further platen having a second mold chase with a second mold chase surface to clamp a substrate, which is held against a substrate-facing surface relating to either the first or second mold chase surface,
- 10 between the first and second mold chase surfaces to define at least one mold cavity with respect to the substrate; wherein the platen further comprises a rotational mounting device on which either the first or second mold chase is rotatable about at least one axis passing through the centre of the substrate-facing surface to adjust the relative arrangement of the first and second mold chase surfaces. Also disclosed is a
- 15 molding press comprising the platen, and the further platen cooperating with the platen.

[FIG. 1]